



## 工程验证

主要材料/BOM 清单信息(Information of Material/BOM list):

Material			customer Part No.	Part No.	Dimension	Note
1	基板	FBGA200B(145100)1298001	/	/	240X76. 3X0. 18	深圳和美精艺
2	晶圆	Z42M	/	/	7948*6476*60	3 inch tray
3	DAF膜	来料	/	/	/	/
4	线材	Au 16	/	/	0.65mil	深圳若榆半导体材料科技有限公司
5	塑封料	EME-G750N Type B	/	/	fillsize 55um, 密度1.99	住友电木
6	植球助焊剂	WF-6317P	/	/	/	/
7	植球	SAC305	/	/	0.35 MM	千纳成

履历		
序号	内容	日期
1	新发行	2025.11.25
2	增加键合局部放大示意图	2025.11.29

拟制 Prepared by	NINGLIN	制图日期 Create Date	2025/11/29	生效日期 Effective Date		客户确认签字/盖章: Customer Signature
研发审核 R&d check		产品工程审核 Product engineering check		批准 Approved by		

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池州华宇电子科技股份有限公司

CHI ZHOU HISEMI ELECTRONICS TECHNOLOGY CO.,LTD  
焊线图纸 Bonding Diagram

客户代码  
Customer No.

1298

线图号  
Drawing No.

HY-PX-1298-001 A

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产品名称  
Product Type

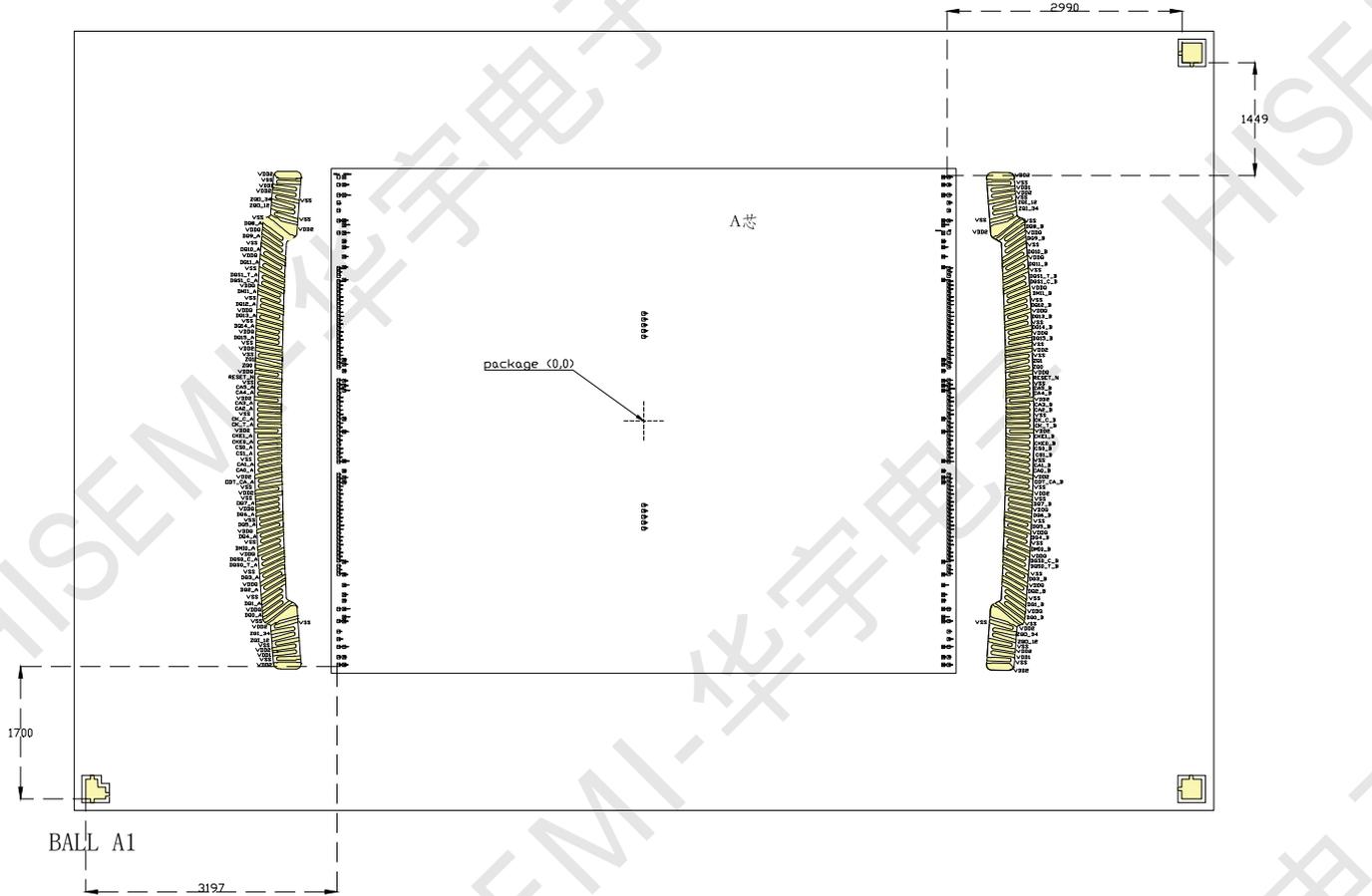
Z42M

封装外型  
PKG Type

FBGA200B(14.5X10x1.1-P0.65)

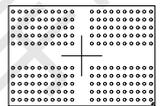
装片示意:

工程验证



注意:

1. 装片方向见附页3



BALL A1

底部示意图

框架传送方向 (装片):

L/F Direction (D/A): (三圆孔朝上)

实物图:

Chip photo:

特殊说明 Special Instructions:

注意: DB装片精度±25um。



说明 Instructions	粘片胶类型 epoxy type	芯片名称 Die name	芯片尺寸 Die Size	最小焊盘尺寸 Min BPO (um <sup>2</sup> )	最小焊盘间距 Min BPP(um)	铝垫厚度(um) Pad Thickness	焊盘下是否有 电路 Circuit under Pad	划片道宽度 Street line (um)	晶圆尺寸 Wafer Size	是否激光切割 If laser?	减薄厚度 (um) Wafer Thickness
A芯: DIE A	来料DAF	Z42M	7948*6476(um <sup>2</sup> ) 312.9*25.5(mil <sup>2</sup> )	42*42	69	/	/	/	/	/	60

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PKG Type

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实物方向示意：  
(按照此方向装片)

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pad 1



注意此处pad更接近芯片短边pad

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PKG Type

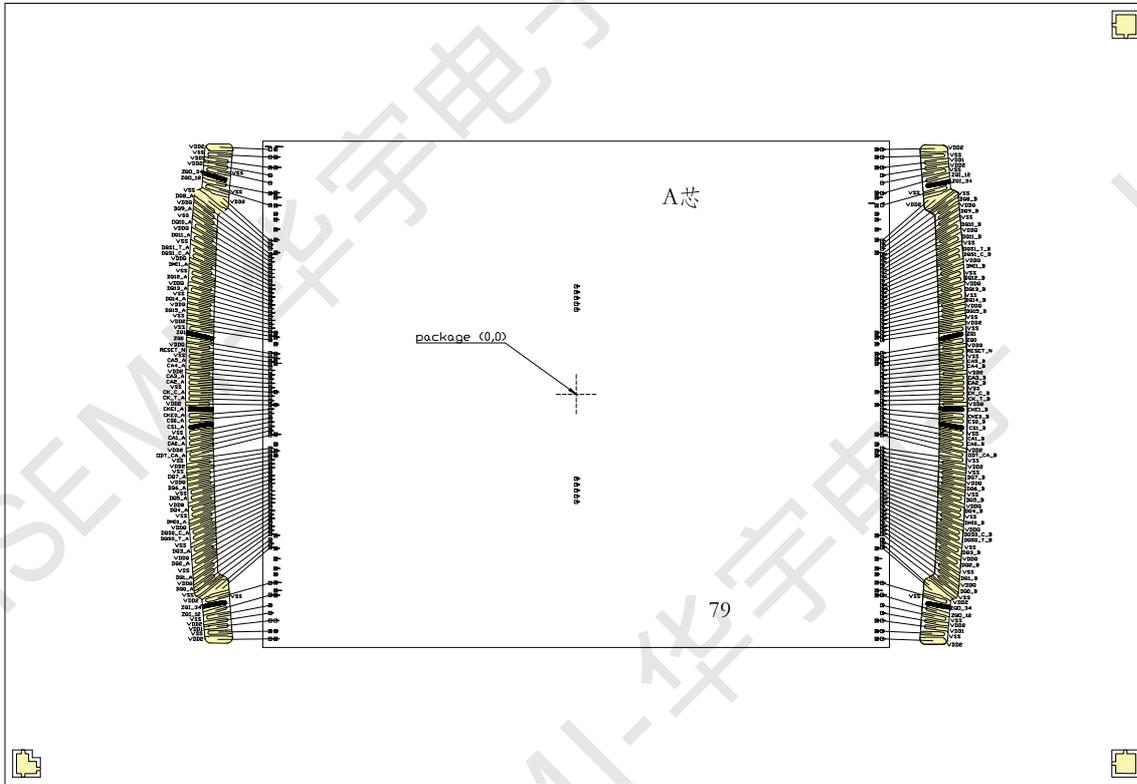
FBGA200B(14.5X10x1.1-P0.65)

焊线种类 Wire Type	焊线直径(um) Wire Diameter	焊线根数 NO. of wire	焊线总长(um) Total wire length	最长线长(um) Longest wire length	最短线长(um) Shortest wire length	塑封料型号(绿色环保) Compound Type (Green)	基板编码 Substrate No.
金丝 Au	16	172	205529	1052	636	首选(Preferred): EME-G750N TYPE B 备选(Optional):	FBGA200B(145100)1298001
客户图号 Customer drawing NO.							

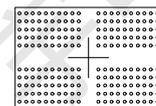
键合示意:



工程验证



BALL A1



BALL A1  
底部示意图

框架传送方向(装片): L/F Direction (D/A): (三圆孔朝上)	实物图: Chip photo:	特殊说明 Special Instructions: 注意: 数字为不打线pad个数。

说明 Instructions	粘片胶类型 epoxy type	芯片名称 Die name	芯片尺寸 Die Size	最小焊盘尺寸 Min BPO (um <sup>2</sup> )	最小焊盘间距 Min BPP(um)	铝垫厚度(um) Pad Thickness	焊盘下是否有 电路 Circuit under Pad	划片道宽度 Street line (um)	晶圆尺寸 Wafer Size	是否激光切割 IF laser?	减薄厚度 (um) Wafer Thickness
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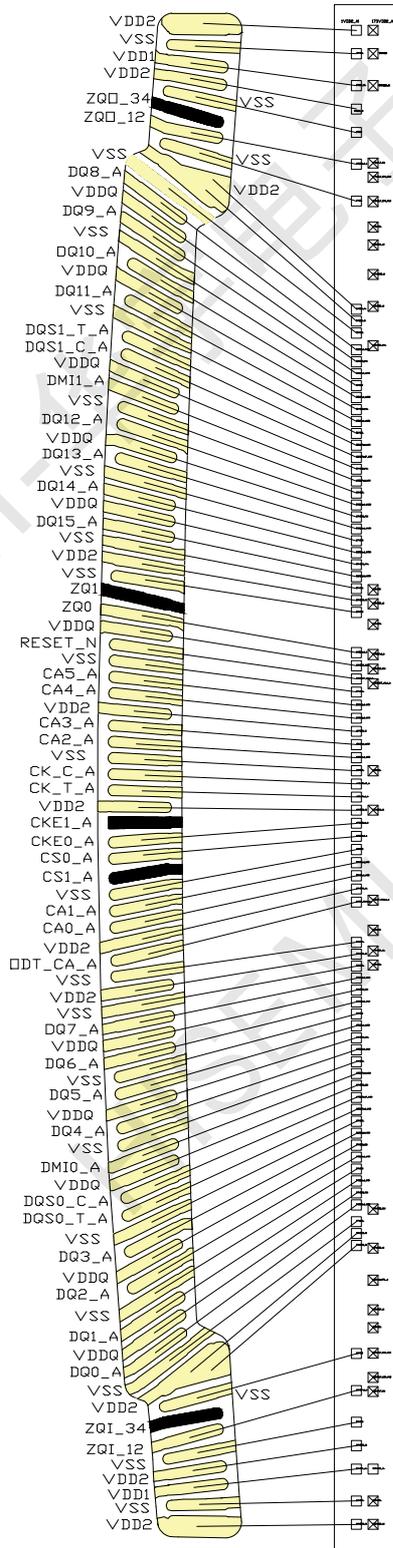
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键合示意 (左) :  
 比例: 3:1

工程验证



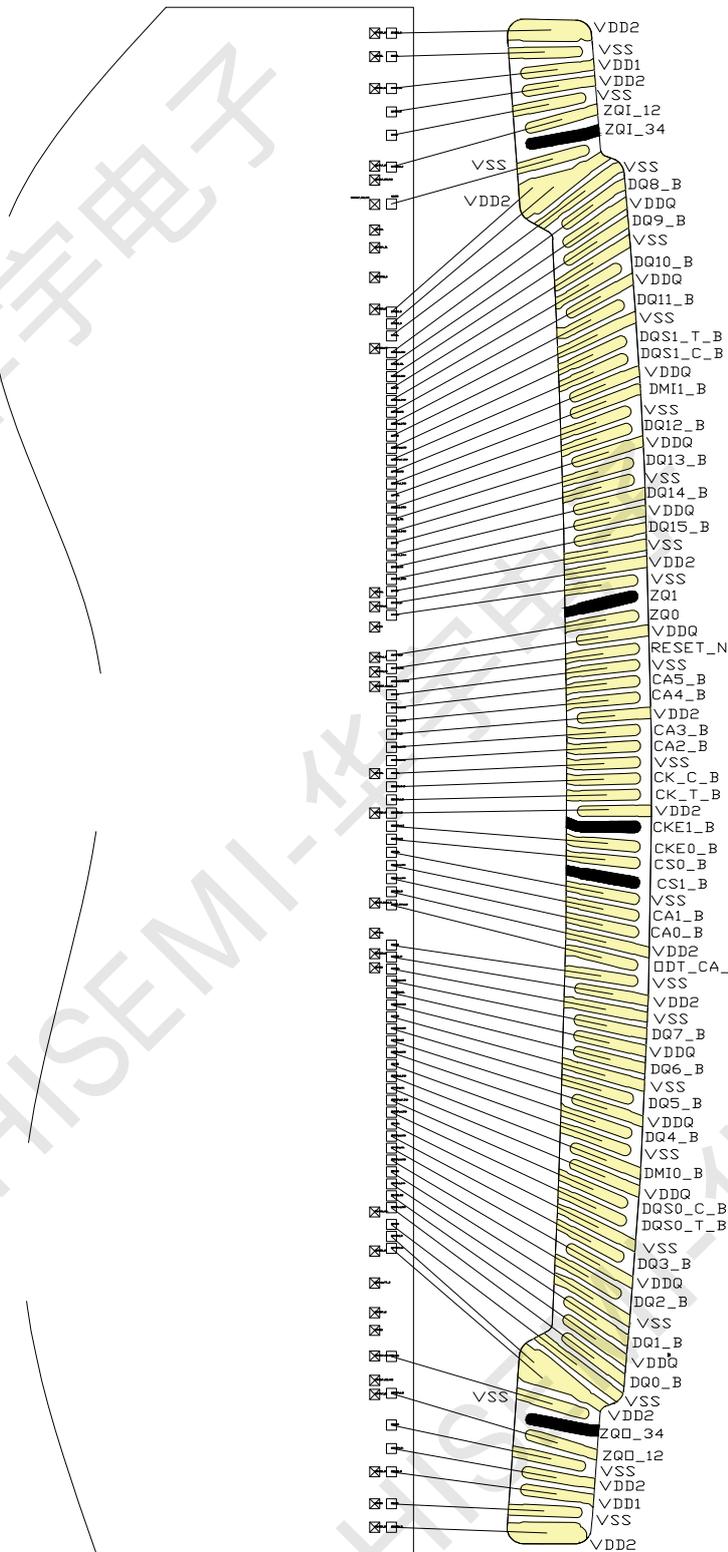
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键合示意 (右):

工程验证



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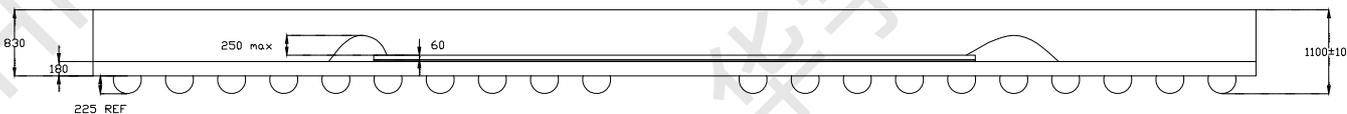
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